



US00D510325S

(12) **United States Design Patent**
Lin et al.

(10) **Patent No.:** **US D510,325 S**
(45) **Date of Patent:** **** Oct. 4, 2005**

(54) **THERMAL MODULE**

(75) Inventors: **Chi-Chang Lin**, Lujhou (TW);
Chih-Yuan Cheng, Banciao (TW);
Heng-Tsung Wang, Taipei (TW)

(73) Assignee: **ASUSTek Computer Inc.**, Taipei (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/196,460**

(22) Filed: **Dec. 31, 2003**

(30) **Foreign Application Priority Data**

Oct. 15, 2003 (TW) 92306267

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Search** D13/179; 165/80.3,
165/121, 122, 146, 104.33, 180, 185; 174/16.3;
257/706, 707, 718-722; 361/271, 274.3,
695, 697, 700, 702, 704, 709, 710, 711,
514, 719

(56) **References Cited**

U.S. PATENT DOCUMENTS

6,137,681 A * 10/2000 Lu 361/697

6,412,546 B1 * 7/2002 Lin et al. 165/80.3
6,480,387 B1 * 11/2002 Lee et al. 361/704
6,560,113 B1 * 5/2003 Ma 361/719
2003/0081382 A1 * 5/2003 Lin 361/697
2003/0117773 A1 * 6/2003 Cheng et al. 361/700

* cited by examiner

Primary Examiner—Stella Reid
Assistant Examiner—Selina Sikder

(74) *Attorney, Agent, or Firm*—Rabin & Berdo, P.C.

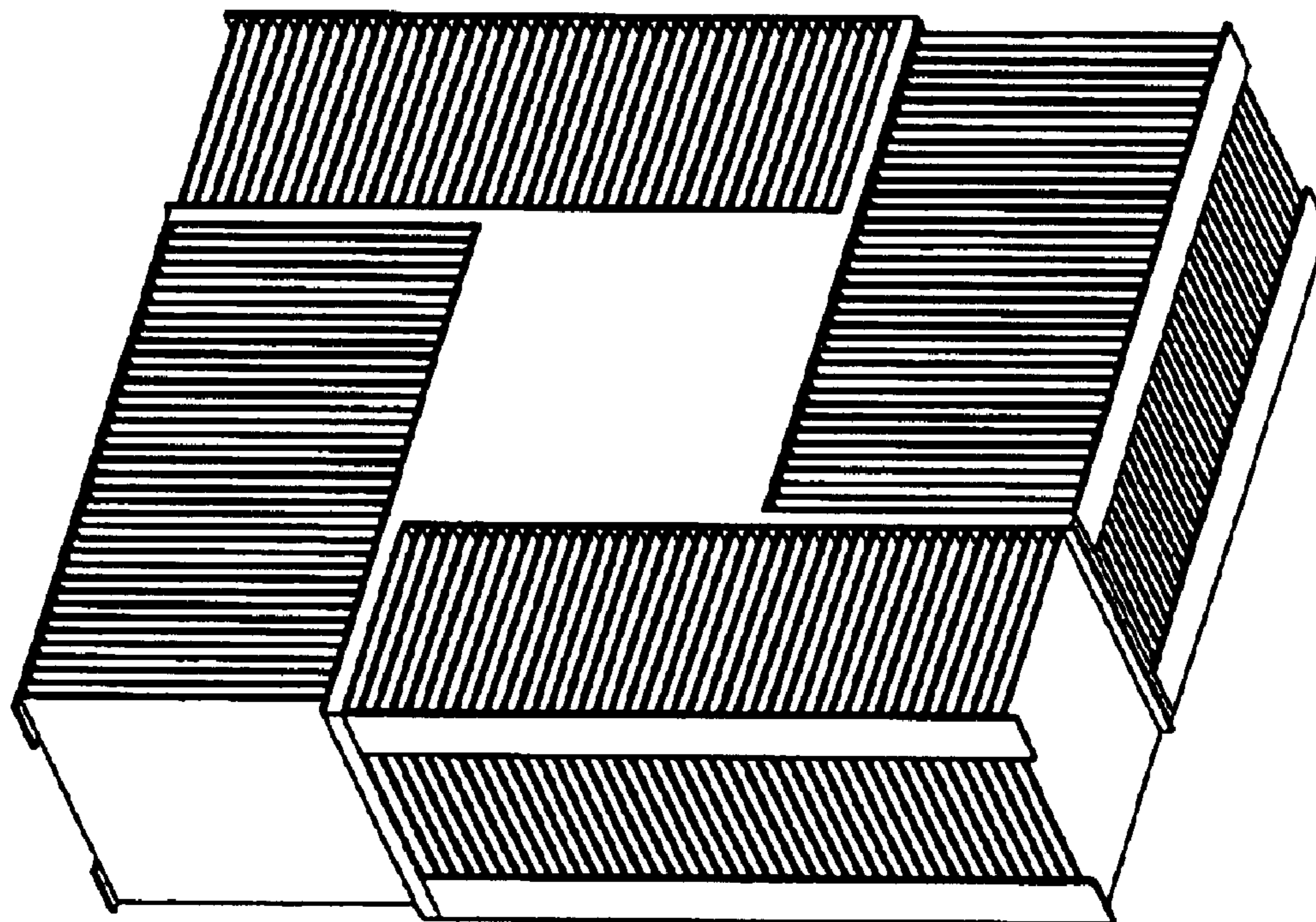
(57) **CLAIM**

The ornamental design for a thermal module, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a thermal module showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof; and,
FIG. 7 is a rear elevational view thereof.

1 Claim, 7 Drawing Sheets



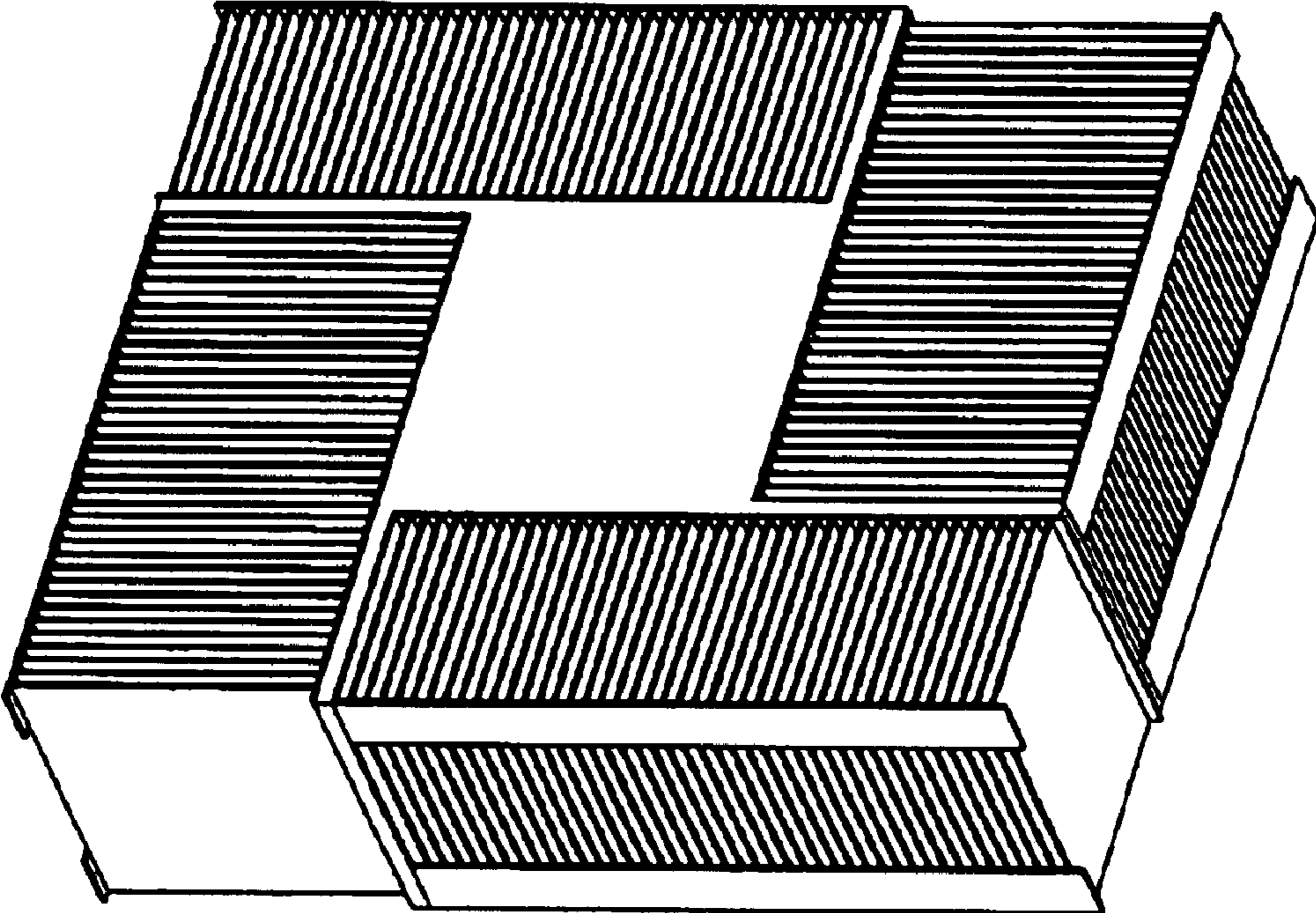


FIG. 1

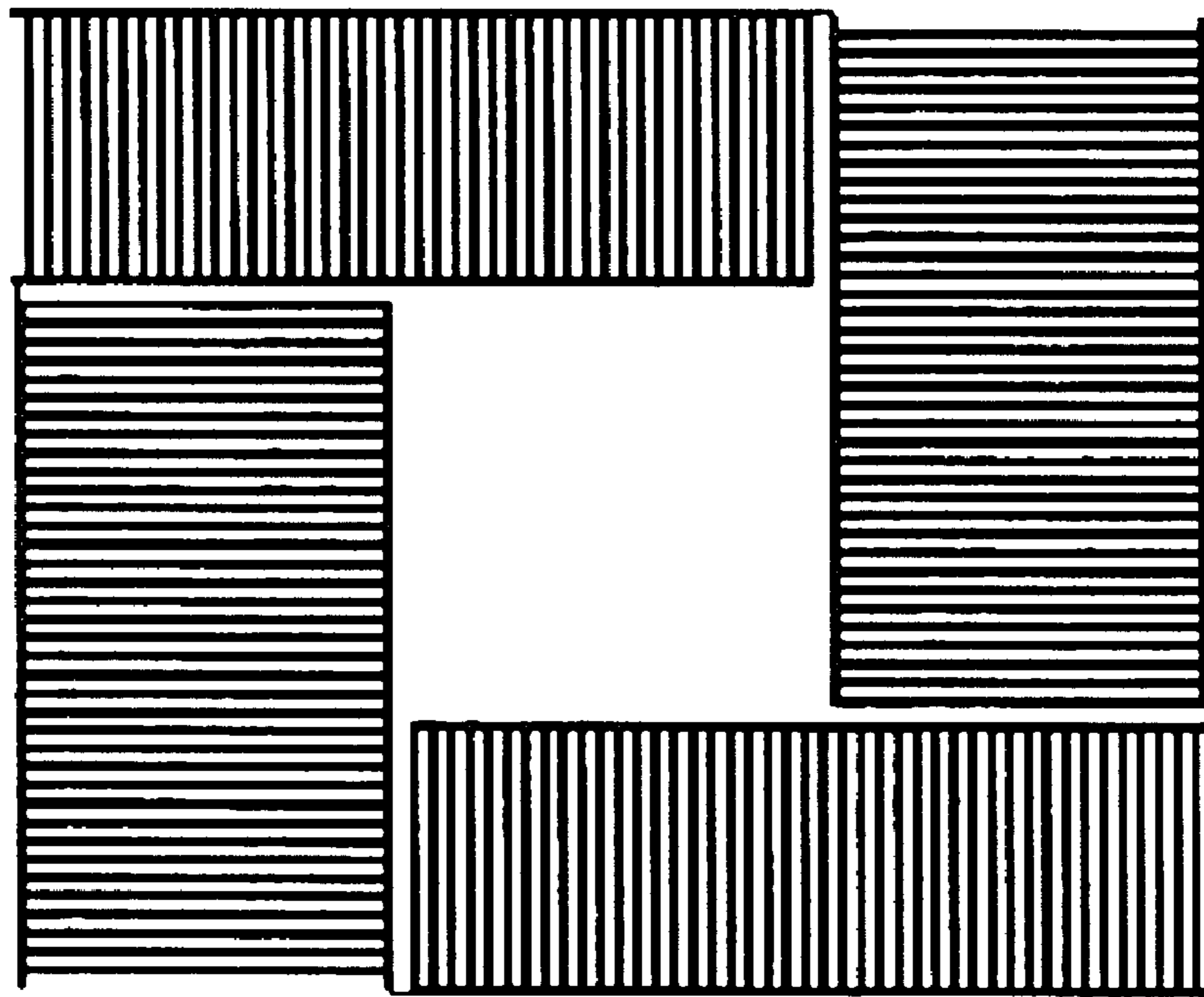


FIG. 2

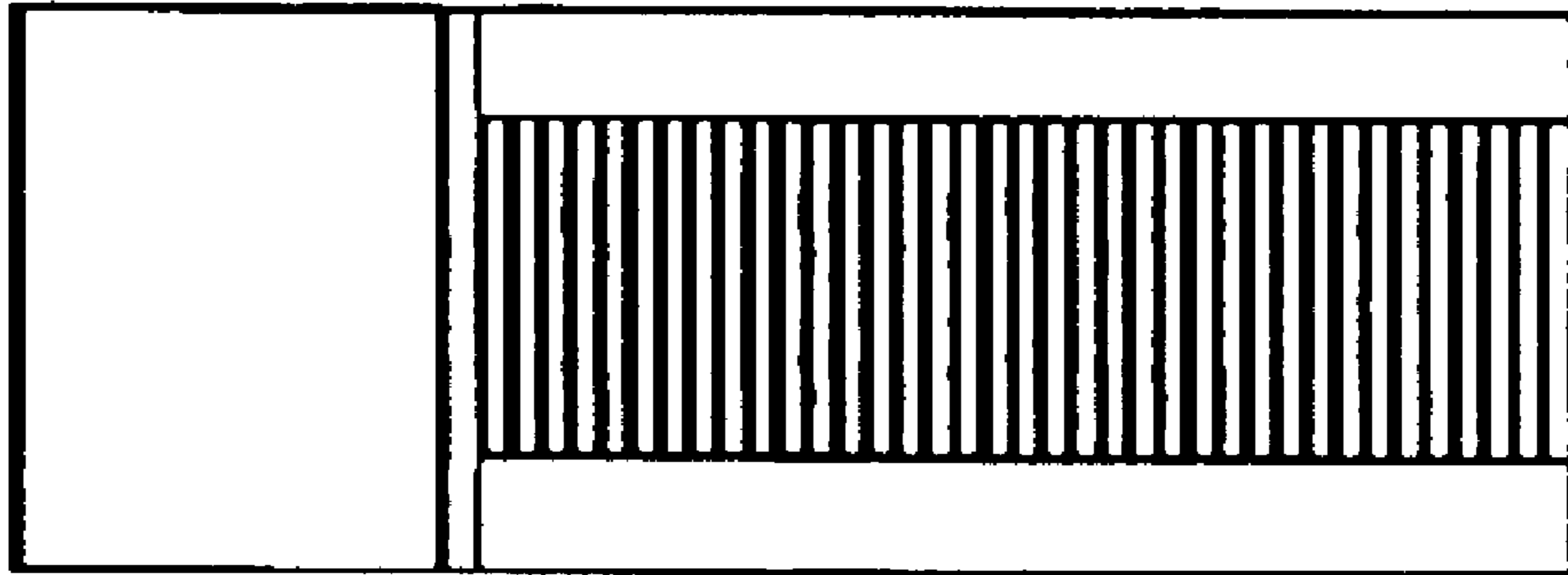


FIG. 3

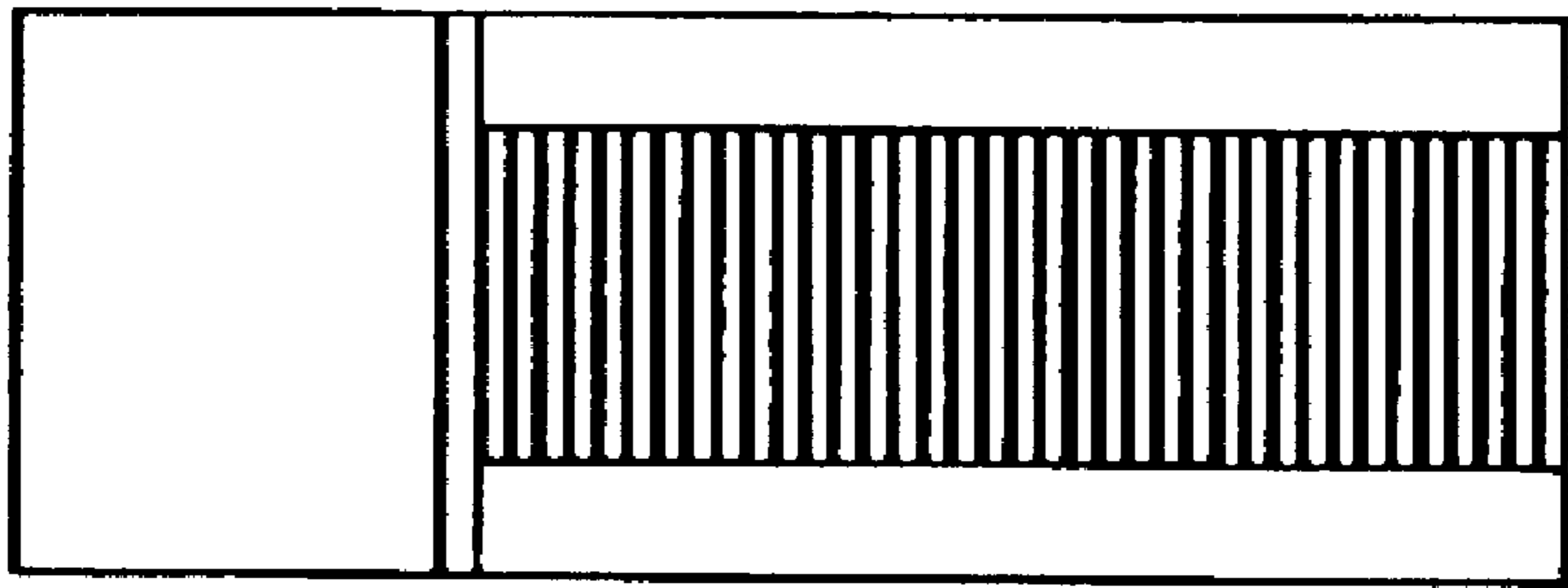


FIG. 4

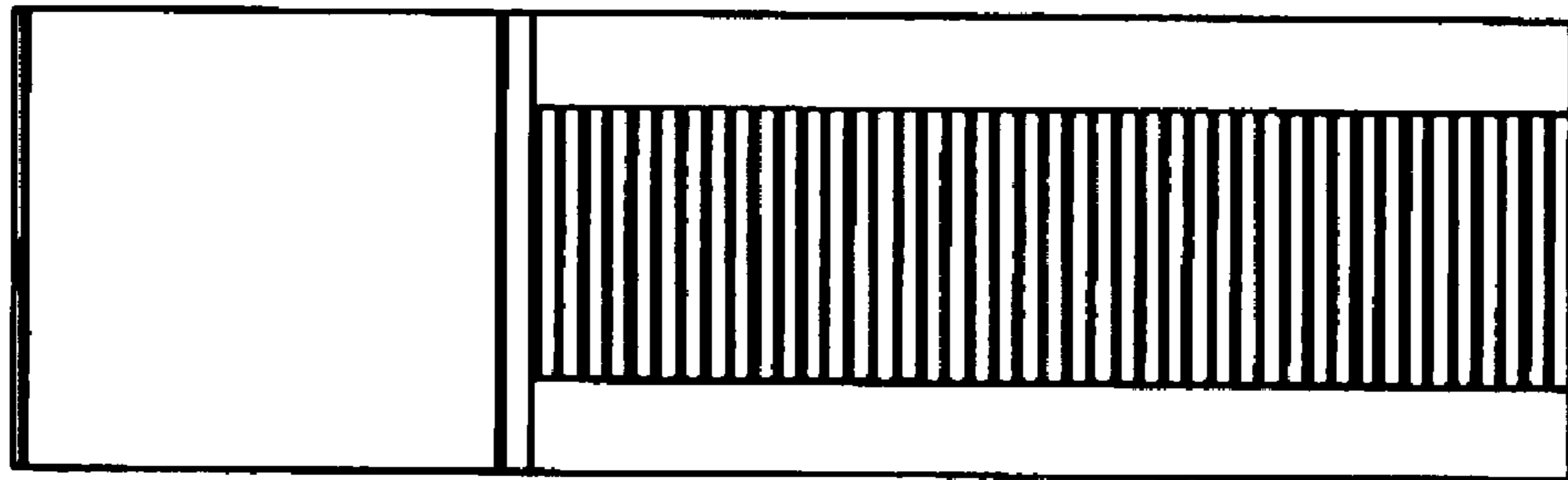


FIG. 5

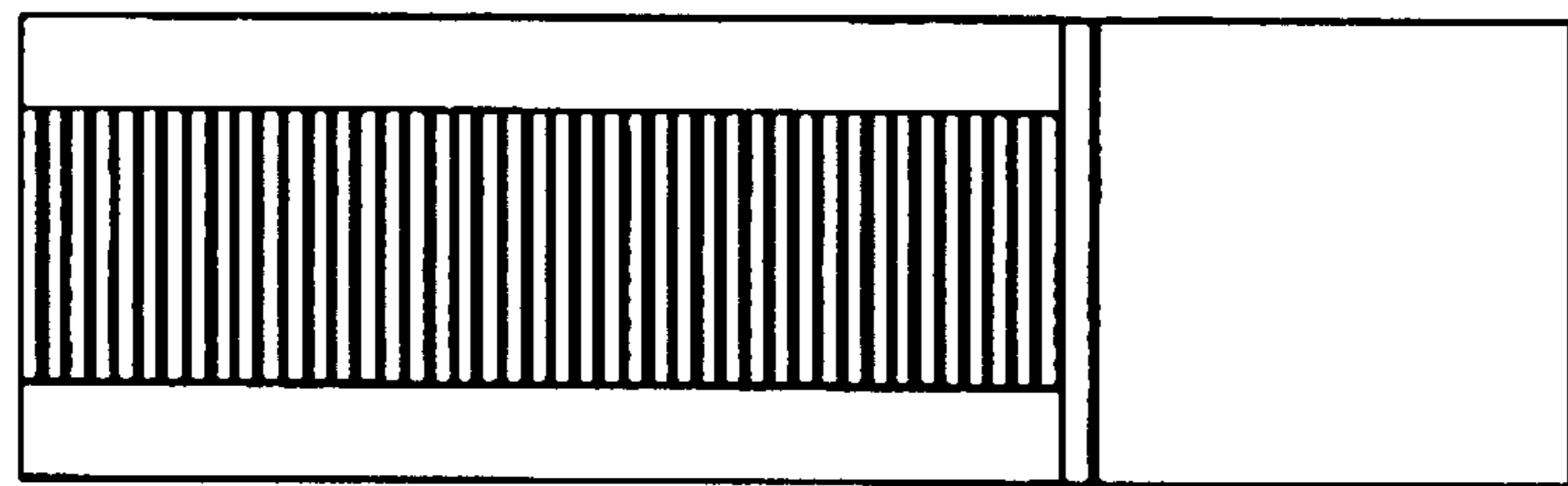


FIG. 6

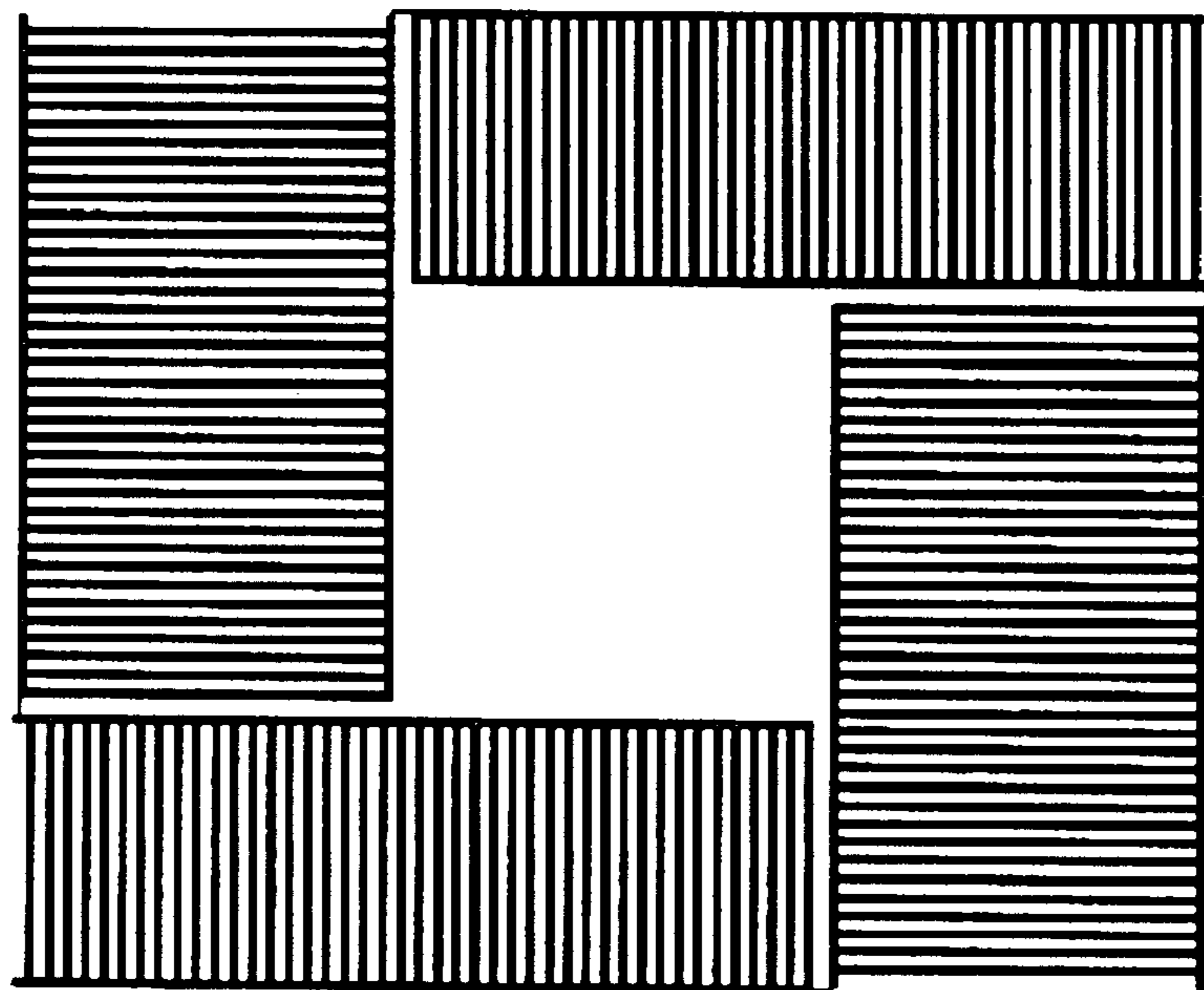


FIG. 7